

Moisture sensitivity level 1
Reverse voltage 75V
Average forward current 200mA

Signal switching

SOT-23
Tin plated leads, solderable per
J-STD-002 and JESD22-B102

($T_a=25$ Unless otherwise specified)

Device marking code			JZ
Repetitive peak reverse voltage	V_{RRM}	V	85
Forward current, per leg	I_F	mA	200
Non-repetitive surge peak forward current @ t=8.3ms half-sine wave	I_{FSM}	A	2
Non-repetitive surge peak forward current @ t=1ms square wave			2
Power dissipation	P_D	mW	225
Junction temperature	T_J		-55 to +150
Storage temperature	T_{STG}		-55 to +150



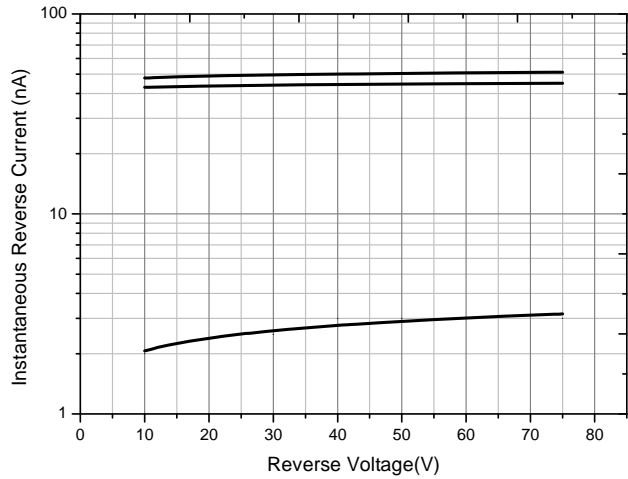
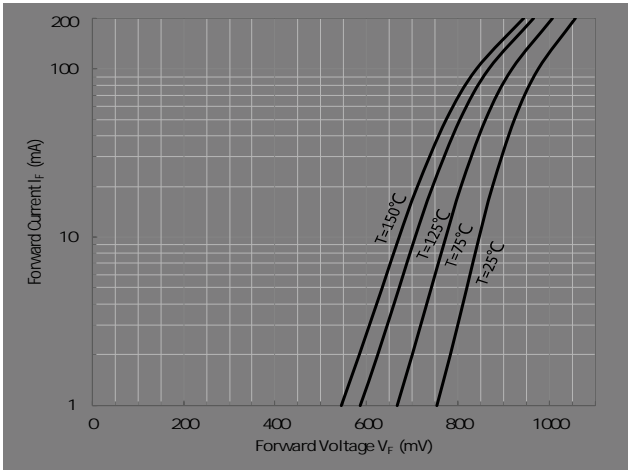
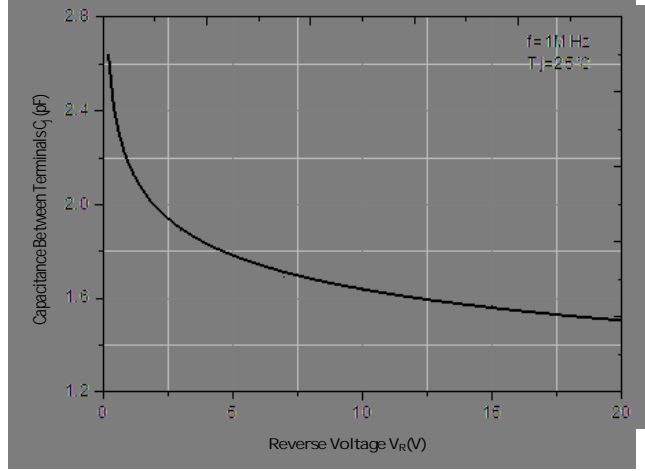
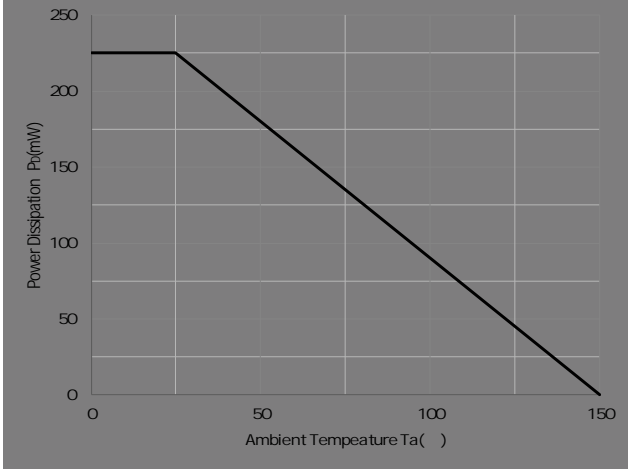
(T_a=25 Unless otherwise specified)

Reverse voltage	V _R	V	I _R =100uA	75		
Forward voltage	V _{F1}	V	I _F =1mA			0.9
	V _{F2}	V	I _F =10mA			1.0
	V _{F3}	V	I _F =50mA			1.1
	V _{F4}	V	I _F =150mA			1.25
Reverse leakage current	I _R	nA	V _R =75V			5
Junction capacitance	C _j	pF	V _R =0V, f=1MHz			4
Reverse recovery time	T _{rr}	us	I _F =I _R =10mA I _{rr} =1mA , R _L =100			3

Thermal resistance, junction-to-ambient	R _{J-A} ⁽¹⁾	/W	556
Thermal resistance, junction-to-case	R _{J-C} ⁽¹⁾	/W	445

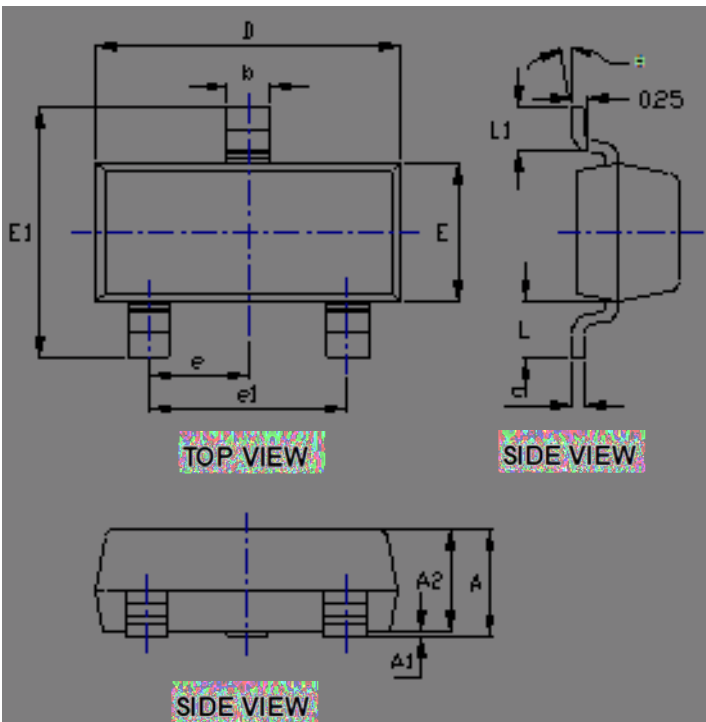
Note:

- 1 Device mounted on PCB, single-sided copper with standard footprint

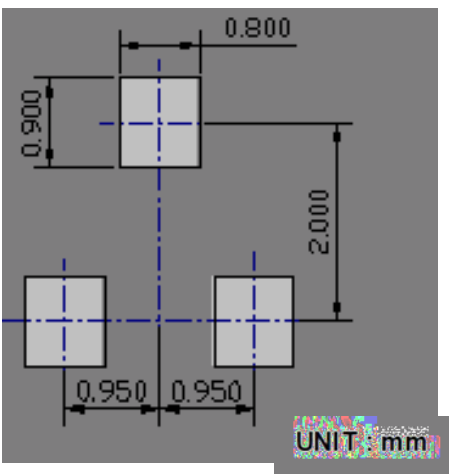




BAW156	F2	Approximate 0.008	3000	30000	120000	7" reel
BAW156	F4	Approximate 0.008	10000	/	210000	13" reel



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
∠	0°	8°	0°	8°





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